

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7792397

| | |
|---|--------------------------|
| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| VARUN SHARMA | 09/02/2021 |
| DANIELE CHIAPPE | 08/26/2021 |
| EVA TOIS | 08/25/2021 |
| VIRAJ MADHIWALA | 08/25/2021 |
| MARKO TUOMINEN | 09/03/2021 |
| CHARLES DEZELAH | 08/26/2021 |
| MICHAEL GIVENS | 08/25/2021 |
| TOM BLOMBERG | 02/08/2023 |
| RECEIVING PARTY DATA | |
| Name: | ASM IP HOLDING B.V. |
| Street Address: | VERSTERKERSTRAAT 8 |
| City: | ALMERE |
| State/Country: | NETHERLANDS |
| Postal Code: | 1322 AP |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 17472981 |
| CORRESPONDENCE DATA | |
| Fax Number: | (602)470-2434 |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | |
| Phone: | 6024705707 |
| Email: | asia.gul@asm.com |
| Correspondent Name: | PATRICK LEE |
| Address Line 1: | 3440 E. UNIVERSITY DRIVE |
| Address Line 4: | PHOENIX, ARIZONA 85034 |
| ATTORNEY DOCKET NUMBER: | 100175US02 |
| NAME OF SUBMITTER: | ASIA GUL |
| SIGNATURE: | /Asia Gul/ |

| | |
|--|------------|
| DATE SIGNED: | 02/13/2023 |
| Total Attachments: 9 source=100175US02 Assignment Executed#page1.tif source=100175US02 Assignment Executed#page2.tif source=100175US02 Assignment Executed#page3.tif source=100175US02 Assignment Executed#page4.tif source=100175US02 Assignment Executed#page5.tif source=100175US02 Assignment Executed#page6.tif source=100175US02 Assignment Executed#page7.tif source=100175US02 Assignment Executed#page8.tif source=100175US02 Assignment Executed#page9.tif | |

ASSIGNMENT

WHEREAS, Varun Sharma, a citizen of India and a resident of Helsinki, FI; Daniele Chiappe, a citizen of Italy and a resident of Espoo, FI; Eva Tois, a citizen of Finland and a resident of Espoo, FI; Viraj Madhiwala, a citizen of India and a resident of Helsinki, FI; Marko Tuominen, a citizen of Finland and a resident of Helsinki, FI; Charles Dezelah, a citizen of United States of America and a resident of Helsinki, FI; Michael Givens, a citizen of United States of America and a resident of Oud-Heverlee, BE; Tom Blomberg, a citizen of Finland and a resident of Vantaa, FI;

(collectively, “WE” or “ASSIGNOR”) have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to SILICON OXIDE DEPOSITION METHOD (collectively, the “INVENTIONS”) for which WE have executed and/or may execute one or more patent applications therefore; and

WHEREAS, ASM IP HOLDING B.V. (hereinafter “ASSIGNEE”), a corporation having a place of business at Versterkerstraat 8, Almere, 1322 AP, Netherlands, desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all patent applications therefore, and all patents that have granted or may be granted hereafter thereon, including, but not limited to, those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed and transferred, and by these presents do hereby sell, assign, convey and transfer, unto ASSIGNEE, its successors, its legal representatives and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefore that may have been filed or may be filed hereafter for said INVENTIONS (including but not limited Application No(s). 17/472,981, filed on September 13, 2021, as Docket No. 100175US02 (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known)) and all rights of priority under International Conventions, Treaties, and Agreements, all utility applications, national phase applications, utility model applications, divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications and design applications thereof, and all issued patents which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon;

AND WE DO HEREBY authorize and request any Official of any country or countries whose duty it is to issue patents on applications or registrations, to issue all patents for said

Application Serial No.: _____

Docket No.: 100175US02

Filing Date: _____

Title: SILICON OXIDE DEPOSITION METHOD

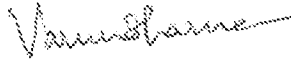
INVENTIONS to ASSIGNEE, its successors, its legal representatives, and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover and retain damages and any ongoing or prospective royalties to which WE may be entitled, or form any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives, and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries.

EXECUTED as of the date(s) below by ASSIGNOR:

Varun Sharma



Signature

02, September, 2021

Date

Daniele Chiappe

Signature

Date

Eva Tois

Signature

Date

Viraj Madhiwala

Signature

Date

Application Serial No.: _____

Docket No.: 100175US02

Filing Date: _____

Title: SILICON OXIDE DEPOSITION METHOD

INVENTIONS to ASSIGNEE, its successors, its legal representatives, and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover and retain damages and any ongoing or prospective royalties to which WE may be entitled, or form any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives, and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries.

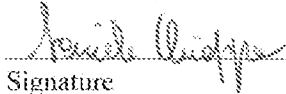
EXECUTED as of the date(s) below by ASSIGNOR:

Varun Sharma

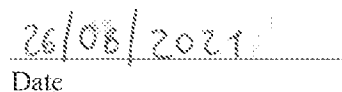
Signature

Date

Daniele Chiappe



Signature



Date

Eva Tois

Signature

Date

Viraj Madhiwala

Signature

Date

Application Serial No.: _____

Docket No.: 100175US02

Filing Date: _____

Title: SILICON OXIDE DEPOSITION METHOD

INVENTIONS to ASSIGNEE, its successors, its legal representatives, and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover and retain damages and any ongoing or prospective royalties to which WE may be entitled, or form any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives, and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries.

EXECUTED as of the date(s) below by ASSIGNOR:

Varun Sharma

Signature

Date

Daniele Chiappe

Signature

Date

Eva Tois

Eva Tois

25-Aug-2021

Signature

Date

Viraj Madhiwala

Signature

Date

Application Serial No.: _____

Docket No.: 100175US02

Filing Date: _____

Title: SILICON OXIDE DEPOSITION METHOD

INVENTIONS to ASSIGNEE, its successors, its legal representatives, and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover and retain damages and any ongoing or prospective royalties to which WE may be entitled, or form any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives, and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries.

EXECUTED as of the date(s) below by ASSIGNOR:

Varun Sharma

Signature

Date

Daniele Chiappe

Signature

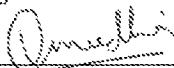
Date

Eva Tois

Signature

Date

Viraj Madhiwala



Signature

25-08-2021

Date

Application Serial No.: _____

Docket No.: 100175US02

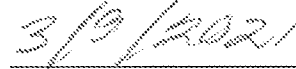
Filing Date: _____

Title: SILICON OXIDE DEPOSITION METHOD

Marko Tuominen



Signature



Date

Charles Dezelah

Signature

Date

Michael Givens

Signature

Date

Tom Blomberg

Signature

Date

Application Serial No.: _____

Docket No.: 100175US02

Filing Date: _____

Title: SILICON OXIDE DEPOSITION METHOD

Marko Tuominen

Signature

Date

Charles Dezelah



Signature


Date

Michael Givens

Signature

Date

Tom Blomberg

Signature

Date

Application Serial No.: _____

Docket No.: 100175US02

Filing Date: _____

Title: SILICON OXIDE DEPOSITION METHOD

Marko Tuominen

Signature

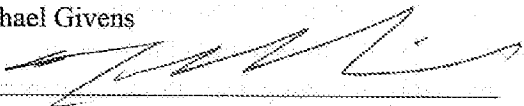
Date

Charles Dezelah

Signature

Date

Michael Givens



Signature

28-AUG-2021
Date

Tom Blomberg

Signature

Date

Application Serial No.: _____

Docket No.: 100175US02

Filing Date: _____

Title: SILICON OXIDE DEPOSITION METHOD

Marko Tuominen

Signature

Date

Charles Dezelah

Signature

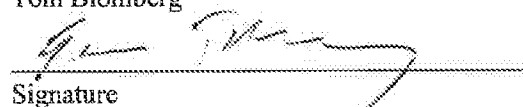
Date

Michael Givens

Signature

Date

Tom Blomberg


Signature


Date